

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	141	(microsphere or microballoon) near2 (sinter\$3)	US-PGPUB; USPAT	OR	ON	2005/10/19 10:00
L2	11	re34887	US-PGPUB; USPAT	OR	ON	2005/10/19 10:06
S1	20151	(semiconductor or substrate or ic or circuit or wiring near board or pwb or pcb) and (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:09
S2	2682	(semiconductor or substrate or ic or circuit or wiring near board or pwb or pcb) and (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere or (hollow or gas or air) near3 (glass or ceramic) near (bubble or sphere)) near6 (coated or coating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 09:19
S3	1584	(substrate or wiring near board or pwb or pcb) near10 (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:10
S4	419	(substrate or wiring near board or pwb or pcb) near10 (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere) near6 (coated or coating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:12
S5	77	(substrate or wiring near board or pwb or pcb) near10 (hollow or void or gass near filled or air near filled) near5 (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere) and (microspheres or micro-spheres or nanospheres or nano-spheres or zeeospheres) near6 (coated or coating or melting near point)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 09:18
S6	1	(semiconductor or ic or circuit or device) near10 (substrate or wiring near board or pwb or pcb) near10 (hollow or void or bubble or gas near filled or air near filled) near5 (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere) and (microspheres or micro-spheres or nanospheres or nano-spheres or zeeospheres) near6 (coated or coating or melting near point)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:22
S7	11	(semiconductor or ic or circuit or device) near10 (substrate or wiring near board or pwb or pcb) same (hollow or void or bubble or gas near filled or air near filled) near5 (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere or (glass or ceramic) near (bubble or sphere)) and (microspheres or micro-spheres or nanospheres or nano-spheres or zeeospheres or (glass or ceramic) near (bubble or sphere)) near6 (matrix or binder or carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 09:23
S8	3	("6042936").URPN.	USPAT	OR	ON	2005/10/04 09:44
S9	961	(semiconductor or substrate or ic or circuit or wiring near board or pwb or pcb) and (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere or microbubbles or micro-bubbles or micropockets) near6 ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 09:32
S10	121	(semiconductor or substrate or ic or circuit or wiring near board or pwb or pcb) and (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere or microbubbles or micro-bubbles or micropockets) near4 ceramic near16 (coated or sprayed or coating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 13:15
S11	441	(gas near filled or hollow) near5 (ceramic) near5 (microsphere or microbubble or micro-sphere or zeeosphere or nanosphere or microvoid) near20 (glass or bpsg or psg or silica or quartz)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 10:40

S12	38	(gas near filled or hollow or gas-filled) near5 (ceramic) near5 (microsphere or microbubble or micro-sphere or zeeosphere or nanosphere or microvoid) near20 (glass or bpsg or psg or silica or quartz) near5 (coated or coating or shell or outer or layer or exterior or sprayed or glaze or glazed)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 10:41
S13	22	("4100140"   "4349456"   "4391646"   "4505720"   "4608434"   "4618525"   "4769440"   "4871401"   "4882370"   "4946908"   "5073526"   "5077241"   "5098781"   "5102749"   "5108958"   "5126192"   "5139856"   "5183972"   "5190738"   "5204289"   "5214005"   "5232775").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/17 10:52
S14	5	("5691059").URPN.	USPAT	OR	ON	2005/10/17 11:00
S15	26	(glass or silica or bpsg or psg or silicon adj oxide or silicon adj dioxide) near2 (coated or coating) near4 ceramic near4 (bubble or droplet or microsphere or microbubble or micro-sphere or microdrop or micropore or nanosphere)	USPAT	OR	ON	2005/10/17 11:01
S16	81	(semiconductor or substrate or ic or circuit or wiring near board or pwb or pcb) and (microspheres or micro-spheres or nanospheres or nano-spheres or zeeosphere or microbubbles or micro-bubbles or micropockets or micropores) near2 ceramic near5 (coated or sprayed or coating or shell)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 13:32
S17	126	ceramic near2 microballoon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 13:32
S18	62	ceramic near2 microballoon near10 (glass or silica or quartz or bpsg or psg or bsg)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/17 13:35
S19	11	(US-20040137259-\$ or US-20030047718-\$ or US-20010021389-\$).did. or (US-6042936-\$ or US-6632511-\$ or US-6821474-\$ or US-6395149-\$ or US-6358532-\$ or US-6210715-\$ or US-5691059-\$ or US-6713867-\$).did.	US-PGPUB; USPAT	OR	ON	2005/10/19 10:06
S20	115	148/33.cor.	US-PGPUB; USPAT	OR	ON	2005/10/17 15:28
S21	136	257/701.cor.	US-PGPUB; USPAT	OR	ON	2005/10/17 15:40
S22	57	257/702.cor.	US-PGPUB; USPAT	OR	ON	2005/10/17 15:50
S23	743	428/403.cor.	US-PGPUB; USPAT	OR	ON	2005/10/17 16:03
S24	54	428/403.cor. and (nanobubble or microbubble or microsphere or micropore or micro-sphere or microcavity or nanosphere or microballoon)	US-PGPUB; USPAT	OR	ON	2005/10/17 15:51
S25	227	428/404.cor.	US-PGPUB; USPAT	OR	ON	2005/10/17 16:21
S26	103	428/405.cor.	US-PGPUB; USPAT	OR	ON	2005/10/17 16:30
S27	43	428/406.cor.	US-PGPUB; USPAT	OR	ON	2005/10/17 16:33
S28	27	427/96.1.cor.	US-PGPUB; USPAT	OR	ON	2005/10/17 16:34
S29	1	(ceramic) near2 (hollow or air or gas) near3 (microbead)	US-PGPUB; USPAT	OR	ON	2005/10/17 16:34
S30	37	(ceramic) near2 (microbubble or microballoon or microsphere or microbead or micropore) near8 (sinter or sintering or sintered)	US-PGPUB; USPAT	OR	ON	2005/10/18 16:52
S31	166	(glass or bpsg or psg or bsg or bpg or silica) near (coating or coated) near4 (microsphere or microbubble or microballoon or micropore or microvoid)	US-PGPUB; USPAT	OR	ON	2005/10/17 16:59

S32	11	(microsphere or microbubble or microballoon or micropore or microvoid) near5 (glaze or glazing or glazed)	US-PGPUB; USPAT	OR	ON	2005/10/19 10:00
S34	14	("3732181"   "4141877"   "4702792"   "5043369"   "5122439"   "5173392"   "5252654"   "5266446"   "5275878"   "5412160"   "5767014"   "5773197"   "5883219").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/18 17:09
S35	79	(substrate or wiring near board or circuit near board or pwb or pcb) and (microbubble or microballoon or microsphere or microbead or micropore or micro-sphere) near2 (sinter or sintering or sintered)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 17:19
S36	503	(substrate or wiring near board or circuit near board or pwb or pcb) and (ceramic) near2 (filler or filling or microparticles or particles) near2 (sinter or sintering or sintered)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 17:20
S37	115	(substrate or wiring near board or circuit near board or pwb or pcb) near10 (ceramic) near2 (filler or filling or microparticles or particles) near (sinter or sintering or sintered)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 17:21
S38	22	(substrate or wiring near board or circuit near board or pwb or pcb) near10 (ceramic) near2 (filler or filling or microparticles or particles) near2 (sinter or sintering or sintered) near10 (binder or matrix or density or loading)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/18 17:22